



DOCKET NO. TS01-167CD

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: **Application of Ying-Lang Wang, et al.**

Confirmation No. **7230**

Serial No.: **10/706,495**

Examiner: **Tuan H. Nguyen**

Filed: **November 12, 2003**

Group Art Unit: **2813**

For: **CMP PROCESS LEAVING NO RESIDUAL OXIDE LAYER OR SLURRY PARTICLES**

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

<p>CERTIFICATE OF MAILING. 37 C.F.R. §1.8(a) I certify that this correspondence and the enclosures mentioned therein are being deposited by First Class U.S. Mail with sufficient postage on the date shown below, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450: <i>Richard A. Paikoff</i> Richard A. Paikoff, Reg. No. 34,892 2/22/05 Date</p>

AMENDMENT AFTER ALLOWANCE, 37 CFR § 1.312

Responsive to the Notice of Allowance and Fee(s) Due, dated December 1, 2004,
Applicants respectfully request that the following corrections be made to the claims:

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 – 26 (cancelled)

Claim 27 (currently amended): A process for performing CMP, comprising:
providing a dielectric layer having a first surface;